Preferred Device

SWITCHMODE™ Power Rectifier

These state-of-the-art devices use the Schottky Barrier principle with a proprietary barrier metal.

Features

- Guardring for Stress Protection
- Maximum Die Size
- 175°C Operating Junction Temperature
- Short Heat Sink Tab Manufactured Not Sheared
- Pb–Free Packages are Available

Mechanical Characteristics:

- Case: Epoxy, Molded, Epoxy Meets UL 94 V-0
- Weight: 1.7 Grams (Approximately)
- Finish: All External Surfaces Corrosion Resistant and Terminal Leads are Readily Solderable
- Lead and Mounting Surface Temperature for Soldering Purposes: 260°C Max. for 10 Seconds
- Device Meets MSL1 Requirements
- ESD Ratings: Machine Model, C (>400 V) Human Body Model, 3B (>8000 V)

MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	V _{RRM} V _{RWM} V _R	30	V
Average Rectified Forward Current(At Rated V_R , $T_C = 134^{\circ}C$)Per DevicePer Device	I _{F(AV)}	30	A
Per Leg		15	
Peak Repetitive Forward Current (At Rated V _R , Square Wave, 20 kHz, T _C = +137°C) Per Leg	I _{FRM}	30	A
Non–Repetitive Peak Surge Current (Surge Applied at Rated Load Conditions, Halfwave, Single Phase, 60 Hz)	I _{FSM}	200	A
Peak Repetitive Reverse Surge Current (2.0 μ s, 1.0 kHz)	I _{RRM}	2.0	A
Storage Temperature Range	T _{stg}	-55 to +175	°C
Operating Junction Temperature (Note 1)	TJ	-55 to +175	°C
Voltage Rate of Change (Rated V_R)	dv/dt	10,000	V/μs
Reverse Energy (Unclamped Inductive Surge) (Inductance = 3 mH, T _C = 25°C)	W	100	mJ

Maximum ratings are those values beyond which device damage can occur. Maximum ratings applied to the device are individual stress limit values (not normal operating conditions) and are not valid simultaneously. If these limits are exceeded, device functional operation is not implied, damage may occur and reliability may be affected.

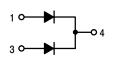
1. The heat generated must be less than the thermal conductivity from Junction-to-Ambient: dP_D/dT_J < $1/R_{\theta JA}$.



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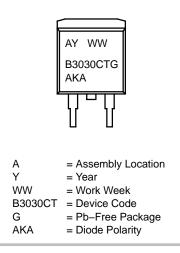
SCHOTTKY BARRIER RECTIFIER 30 AMPERES, 30 VOLTS





D²PAK CASE 418B STYLE 3

MARKING DIAGRAM



ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 2 of this data sheet.

Preferred devices are recommended choices for future use and best overall value.

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THERMAL CHARACTERISTICS (Per Leg)

Characteristic	Symbol	Value	Unit
Thermal Resistance, – Junction-to-Case – Junction-to-Ambient (Note 2)	$R_{ heta JC}$ $R_{ heta JA}$	1.0 50	°C/W

2. When mounted using minimum recommended pad size on FR-4 board.

ELECTRICAL CHARACTERISTICS (Per Leg)

Characteristic	Symbol	Value	Unit
	V _F	0.54 0.47 0.67 0.66	V
Maximum Instantaneous Reverse Current (Note 3), Per Leg (Rated dc Voltage, $T_C = +25^{\circ}C$) (Reverse Voltage = 10 V, $T_C = +150^{\circ}C$) (Rated dc Voltage, $T_C = +150^{\circ}C$)	I _R	0.6 46 145	mA

3. Pulse Test: Pulse Width = 300 μ s, Duty Cycle \leq 2.0%.

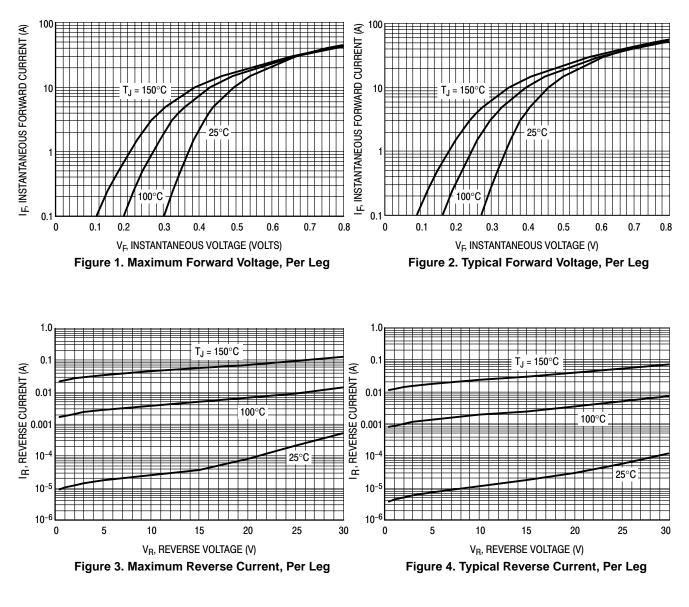
ORDERING INFORMATION

Device	Package	Shipping [†]
MBRB3030CT	D ² PAK	50 Units / Rail
MBRB3030CTG	D ² PAK (Pb–Free)	50 Units / Rail
MBRB3030CTT4	D ² PAK	800 Units / Tape & Reel
MBRB3030CTT4G	D ² PAK (Pb–Free)	800 Units / Tape & Reel

+For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

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ELECTRICAL CHARACTERISTICS



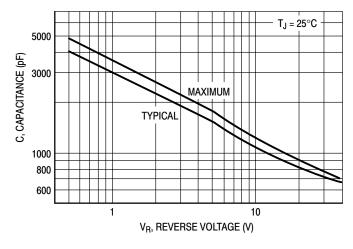
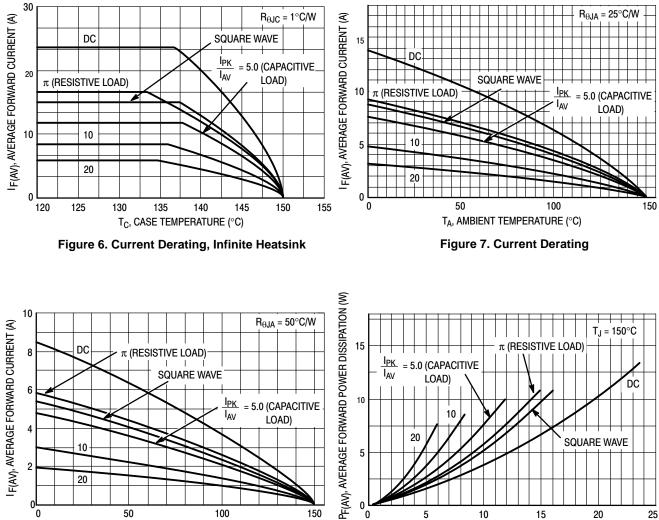


Figure 5. Capacitance

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TYPICAL CHARACTERISTICS



0 150 5 15 20 0 10 IF(AV), AVERAGE FORWARD CURRENT (A) Figure 8. Current Derating, Free Air **Figure 9. Forward Power Dissipation**

25

1.0 +++++ SINGLE PULSE R(t), EFFECTIVE TRANSIENT THERMAL RESISTANCE (NORMALIZED) P_{pk} P_{pk} DUTY CYCLE, D = t_p/t_1 PEAK POWER, P_{pk}, is peak of an 0.1 Ħ TIME equivalent square power pulse. t $\begin{array}{l} \Delta T_{JL} = P_{pk} \bullet R_{0,JL} \left[D + (1 - D) \bullet r(t_1 + t_p) + r(t_p) - r(t_1) \right] \\ \text{where} \\ \Delta T_{JL} = \text{the increase in junction temperature above the lead temperature} \end{array}$ normalized value of transient thermal resistance at time, t, for example, r(t₁ + t_p) = normalized value of transient thermal resistance at time, t₁ + t_p. r(t) ||||0.01 0.1 1.0 10 100 1000 t, TIME (ms)

0L 0

50

100

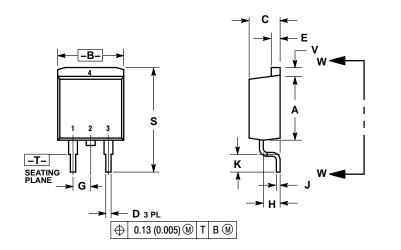
T_A, AMBIENT TEMPERATURE (°C)

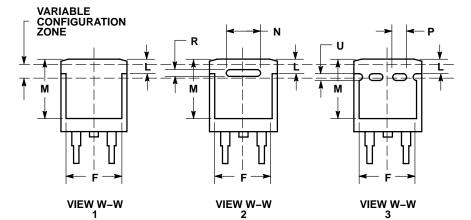
Figure 10. Thermal Response

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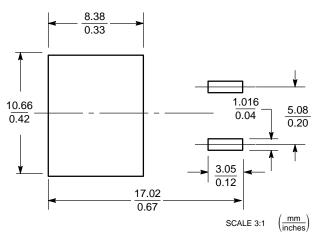
PACKAGE DIMENSIONS

D²PAK 3 CASE 418B-04 ISSUE J





SOLDERING FOOTPRINT*



*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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www.

NOTES: 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982. 2. CONTROLLING DIMENSION: INCH. 3. 418B-01 THRU 418B-03 OBSOLETE, NEW STANDARD 418B-04.

			1	
	INCHES		MILLIN	IETERS
DIM	MIN	MAX	MIN	MAX
Α	0.340	0.380	8.64	9.65
В	0.380	0.405	9.65	10.29
С	0.160	0.190	4.06	4.83
D	0.020	0.035	0.51	0.89
Е	0.045	0.055	1.14	1.40
F	0.310	0.350	7.87	8.89
G	0.100 BSC		2.54 BSC	
н	0.080	0.110	2.03	2.79
J	0.018	0.025	0.46	0.64
κ	0.090	0.110	2.29	2.79
L	0.052	0.072	1.32	1.83
Μ	0.280	0.320	7.11	8.13
Ν	0.197 REF		5.00 REF	
Р	0.079 REF		2.00 REF	
R	0.039 REF		0.99 REF	
S	0.575	0.625	14.60	15.88
V	0.045	0.055	1.14	1.40

STYLE 3: PIN 1. ANODE 2. CATHODE 3. ANODE 4. CATHODE

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